



SPP2321

P-Channel Enhancement Mode MOSFET

DESCRIPTION

The SPP2321 is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

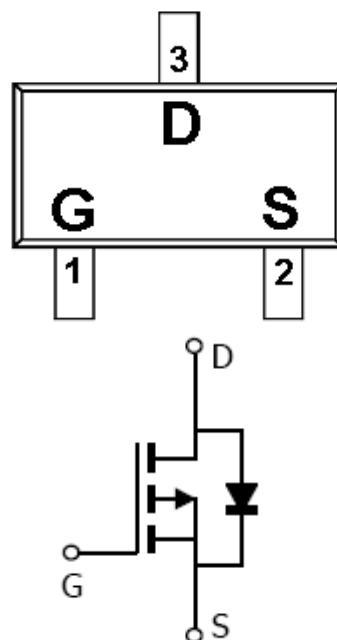
FEATURES

- ◆ -100V/-0.6A, $R_{DS(ON)}=650m\Omega$ @ $V_{GS}=-10V$
- ◆ -100V/-0.4A, $R_{DS(ON)}=760m\Omega$ @ $V_{GS}=-4.5V$
- ◆ Super high density cell design for extremely low $R_{DS(ON)}$
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ SOT-23 package design

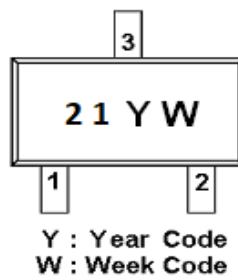
APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

PIN CONFIGURATION(SOT-23)



PART MARKING





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PIN DESCRIPTION

| Pin | Symbol | Description |
|-----|--------|-------------|
| 1 | G | Gate |
| 2 | S | Source |
| 3 | D | Drain |

ORDERING INFORMATION

| Part Number | Package | Part Marking |
|---------------|---------|--------------|
| SPP2321S23RGB | SOT-23 | 21 |

- ※ Week Code : A ~ Z(1 ~ 26) ; a ~ z(27 ~ 52)
- ※ SPP2321S23RGB : Tape Reel ; Pb – Free ; Halogen - Free

ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

| Parameter | Symbol | Typical | Unit |
|---|------------------|---------|------|
| Drain-Source Voltage | V _{DSS} | -100 | V |
| Gate –Source Voltage | V _{GSS} | ±20 | V |
| Continuous Drain Current(T _J =150°C) | TA=25°C | -840 | mA |
| | TA=70°C | | |
| Pulsed Drain Current | I _{DM} | -3.36 | A |
| Continuous Source Current(Diode Conduction) | I _S | -1.0 | A |
| Power Dissipation | TA=25°C | 1.25 | W |
| | TA=70°C | | |
| Operating Junction Temperature | T _J | 150 | °C |
| Storage Temperature Range | T _{STG} | -55/150 | °C |
| Thermal Resistance-Junction to Ambient | R _{θJA} | 120 | °C/W |



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ELECTRICAL CHARACTERISTICS

(TA=25°C Unless otherwise noted)

| Parameter | Symbol | Conditions | Min. | Typ | Max. | Unit |
|---------------------------------|----------------------|---|------|------|------|------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V _{(BR)DSS} | V _{GS} =0V, ID=-250uA | -100 | | | V |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} , ID=-250uA | -1.2 | -1.8 | -2.5 | |
| Gate Leakage Current | I _{GSS} | V _{DS} =0V, V _{GS} =±20V | | | ±100 | nA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =-80V, V _{GS} =0V | | | -1 | uA |
| | | V _{DS} =-80V, V _{GS} =0V T _J =125°C | | | -10 | |
| Drain-Source On-Resistance | R _{DSS(on)} | V _{GS} =-10V, ID=-600mA | | 540 | 650 | mΩ |
| | | V _{GS} =-4.5V, ID=-400mA | | 590 | 760 | |
| Gate resistance | R _g | V _{DS} =-0V, V _{GS} =0V f=1MHz | | 31 | | Ω |
| Forward Transconductance | g _{fs} | V _{DS} =-10V, ID=-0.5A | | 2 | | S |
| Diode Forward Voltage | V _{SD} | I _s =-1A, V _{GS} =0V | | | -1.0 | V |
| Dynamic | | | | | | |
| Total Gate Charge | Q _g | V _{DS} =-50V, V _{GS} =-10V ID=-500mA | | 4.4 | 8.8 | nC |
| Gate-Source Charge | Q _{gs} | | | 0.5 | 1 | |
| Gate-Drain Charge | Q _{gd} | | | 1.8 | 3.6 | |
| Input Capacitance | C _{iss} | V _{DS} =-50V, V _{GS} =0V f=1MHz | | 382 | 760 | pF |
| Output Capacitance | C _{oss} | | | 29 | 60 | |
| Reverse Transfer Capacitance | C _{rss} | | | 18 | 36 | |
| Turn-On Time | t _{d(on)} | V _{DD} =-50V, ID=-0.5A, V _{GS} =-10V, R _G =3.3Ω | | 5 | 10 | nS |
| | t _r | | | 14.5 | 29 | |
| Turn-Off Time | t _{d(off)} | | | 20 | 40 | |
| | t _f | | | 8 | 16 | |



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TYPICAL CHARACTERISTICS

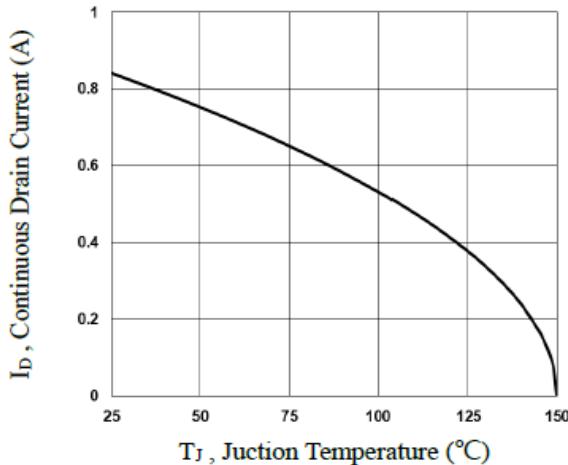


Fig.1 Continuous Drain Current vs. T_J

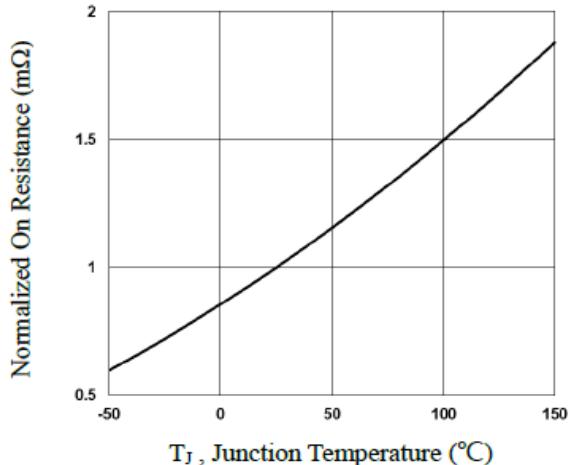


Fig.2 Normalized $R_{DS(ON)}$ vs. T_J

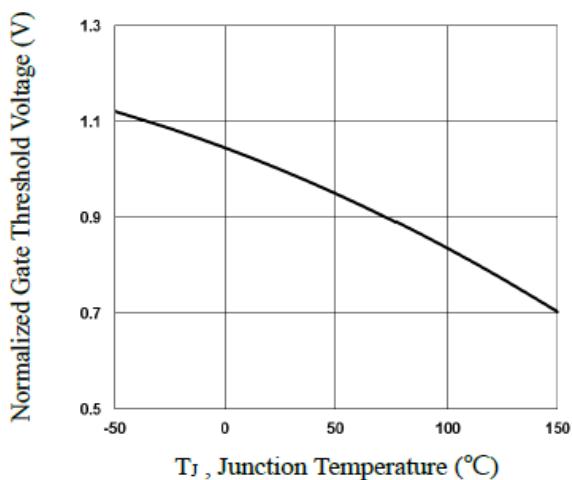


Fig.3 Normalized V_{th} vs. T_J

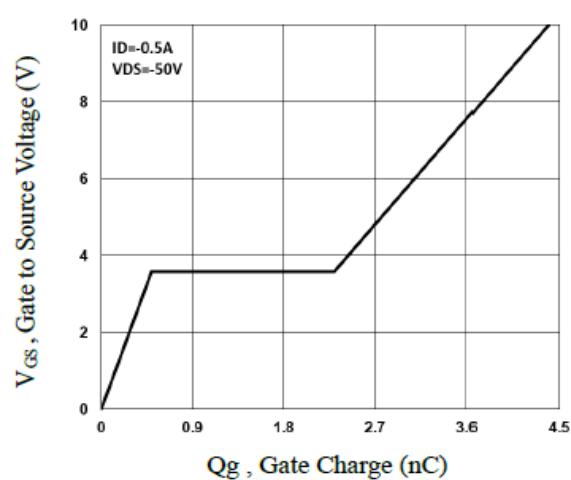


Fig.4 Gate Charge Waveform

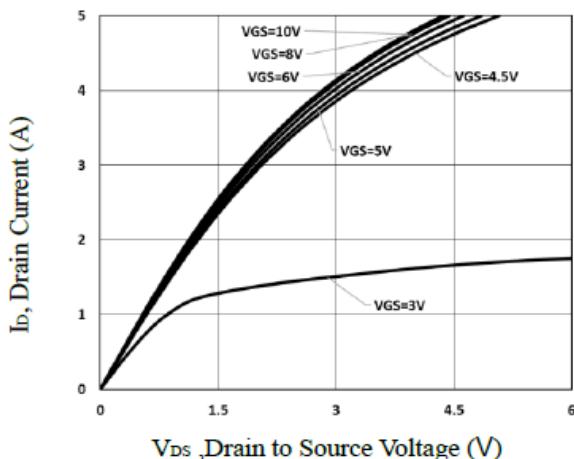


Fig.5 Typical Output Characteristics

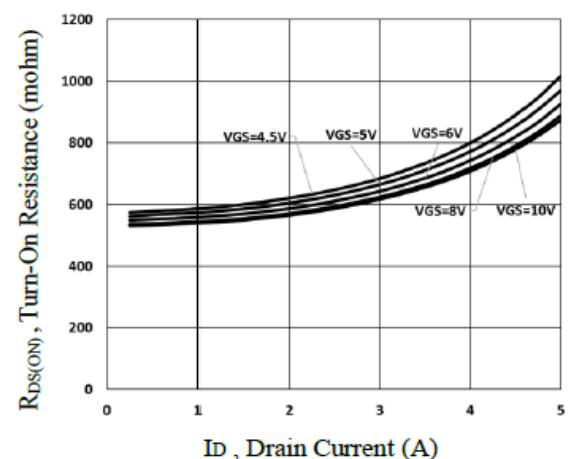


Fig.6 Turn-On Resistance vs. I_D



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TYPICAL CHARACTERISTICS

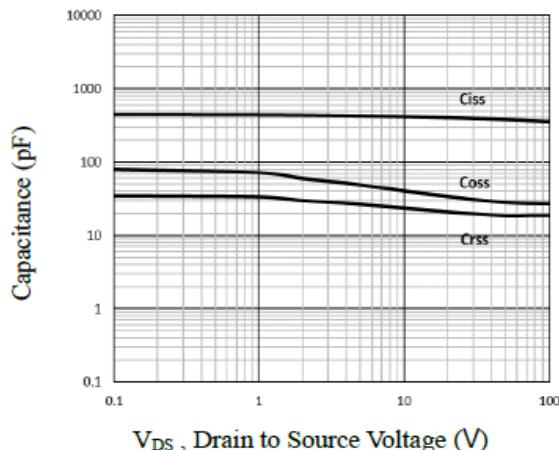


Fig.7 Capacitance Characteristics

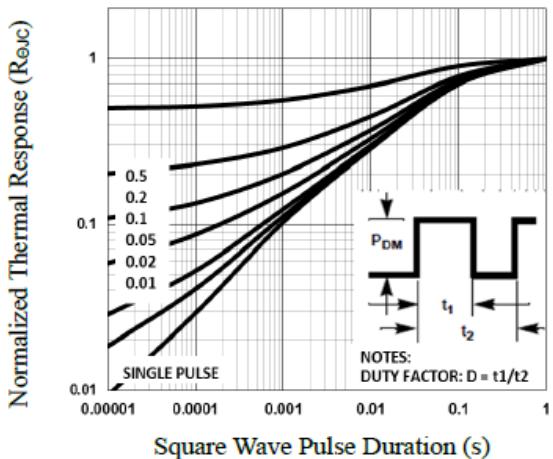


Fig.8 Normalized Transient Response

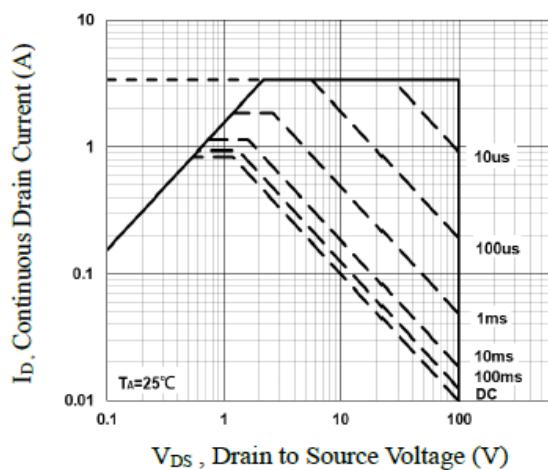


Fig.9 Maximum Safe Operation Area

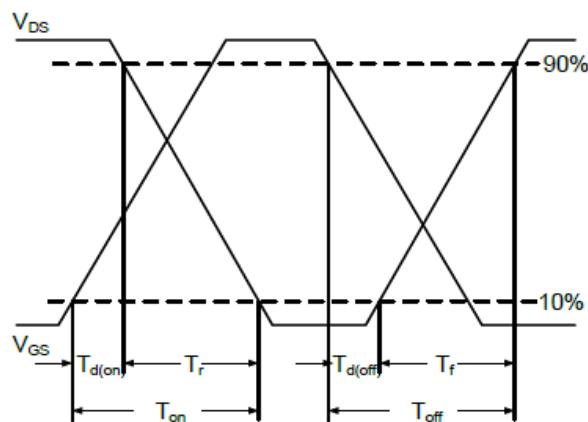


Fig.10 Switching Time Waveform

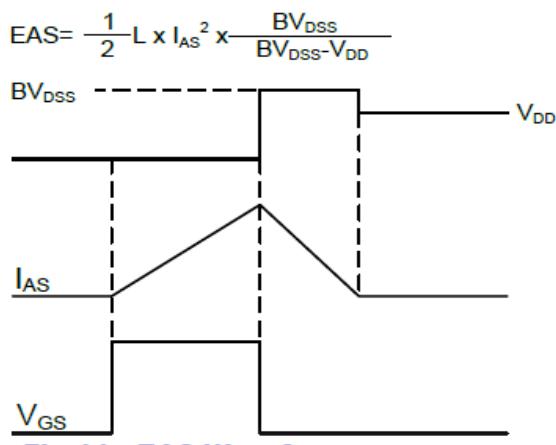


Fig.11 EAS Waveform



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